

IN THE CLAIMS:

Please amend the claims as shown below. The status of the claims after amendment will be as follows:

1. (original) A solder ball assembly for use in the formation of solder bumps comprising a heat-resisting sheet having a plurality of holes, a solder ball disposed in each hole, and an adherent layer disposed within the sheet, the adherent layer being exposed to the interior of each hole in such a manner that the adherent layer contacts and holds the solder ball in the hole.

2. (original) A solder ball assembly as claimed in claim 1 wherein the heat-resisting sheet comprises a material selected from the group consisting of resins, metals, ceramics, paper, and combinations of two or more of these materials.

3. (original) A solder ball assembly as claimed in claim 1 wherein the adherent layer is exposed to the interior of each hole on a wall of the hole.

4. (original) A solder ball assembly as claimed in claim 1 wherein each hole has a bottom surface and the adherent layer is exposed to the interior of the hole on the bottom surface of the hole.

5. (original) A solder ball assembly as claimed in claim 1 wherein each hole is straight and has a wall extending perpendicularly to a surface of the heat-resisting sheet.

6. (original) A solder ball assembly as claimed in claim 1 wherein each hole is tapered and has a diameter which gradually decreases toward a bottom of the hole.

7. (original) A solder ball assembly as claimed in claim 1 wherein each hole is a blind hole.

8. (original) A solder ball assembly as claimed in claim 7 wherein the depth of each blind hole is at least one third the diameter but smaller than the diameter of the solder ball disposed therein.

9. (original) A solder ball assembly as claimed in claim 7 wherein the depth of each blind hole is at least one half the diameter but smaller than the diameter of the solder ball disposed therein.

10. (original) A solder ball assembly as claimed in claim 1 which further comprises a covering placed atop the heat-resisting sheet to cover the solder balls disposed in the holes.

Claims 11 - 17 (cancelled)

18. (original) A method for forming solder bumps on electrodes of a substrate comprising placing a solder ball assembly as claimed in claim 1 upside down on a substrate having a plurality of electrodes with each electrode aligned with one of the holes in the solder ball assembly, heating the substrate and the solder ball assembly to melt the solder balls and transform them within the holes in the solder ball assembly into solder bumps attached to the electrodes, and removing the heat-resisting sheet of the solder ball assembly from the substrate.

19. (original) A sheet for use in forming solder bumps on a substrate having a plurality of electrodes, comprising a heat-resisting sheet having a plurality of holes arranged in the same pattern as the electrodes of a substrate, each hole being capable of receiving a solder ball therein, and an adherent layer disposed within the sheet, the adherent layer being exposed to the interior of each hole in such a manner that when a solder ball is disposed in the hole, the adherent layer contacts and holds the solder ball in the hole.

20. (new) A solder ball assembly as claimed in claim 1 wherein the heat-resisting sheet comprises first and second heat-resisting layers, and the adherent layer is sandwiched between the first and second heat-resisting layers.

21. (new) A solder ball assembly as claimed in claim 1 wherein the adherent layer extends between adjoining holes inside

the heat-resisting sheet.

22. (new) A solder ball assembly as claimed in claim 1 wherein the adherent layer comprises a sheet of an adhesive material.

23. (new) A solder ball assembly as claimed in claim 1 wherein the adherent layer prevents the solder balls from falling out of the holes when the assembly is oriented such that the solder balls would fall out of the holes in the absence of the adherent layer.

24. (new) A solder balls assembly as claimed in claim 10 wherein each solder ball protrudes from the heat-resisting sheet and the covering conforms to the shape of the protruding portions of the solder balls.

25. (new) A sheet as claimed in claim 19 wherein the heat-resisting sheet comprises first and second heat-resisting layers, and the adherent layer is sandwiched between the first and second heat-resisting layers.

26. (new) A sheet as claimed in claim 19 wherein the adherent layer extends between adjoining holes inside the heat-resisting sheet.